

IMT-SA109 SURFACE MOUNT ADHESIVE

IMT-SA109 is a single component, low temperature and fast curable surface mount epoxy adhesive. This SMT adhesive is formulated to bond chips or components onto printed circuit boards. IMT-SA109 cures within a minute at 150°C to prevent component movement during handling or cure. This SMT adhesive offers excellent heat and chemical resistance as well as exhibits good adhesion property to PC boards.

IMT-SA109 is solventless, 100% solid system and does not contain hazardous and/or prohibited substances. It complies to RoHS3, EU directive 2015/863, Substances of Very High Concern (SVHC) published by ECHA as well as Halogen Free.

This SMT adhesive is designed for screen-printing application.

TYPICAL PROPERTIES*

Cure Conditions	1. 150°C for 60s 2. 130°C for 5mins 2. 110°C for 15mins
<u>Physical Properties</u>	
Color	Red before and after cure
Consistency	High viscosity paste
Specific Gravity	1.20
Viscosity @ 1rpm, 25°C	220,000cPs
TI Index @ 0.1/1rpm, 25°C	6.50
Solid Content	100%
Glass transition temperature	133°C
Shore D Hardness	92
Die Shear Strength	> 10Kgf per 3.5 x 2mm die on FR4 substrate
Volume Resistivity	> 1 x 10**14Ωcm
Operating Temperature	-40°C to above 150°C
<u>Ionic Contents</u>	
Chloride, Cl-	≤ 500ppm
Bromine, Br-	Not detected
PVC	Not detected
Pot Life	1 week at room temperature
Shelf Life	12 months at 0°C or below

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* The information is based on data and tests believed to be accurate. In-Mat Technologies (S) Pte Ltd makes no warranties as to its accuracy and assumes no liability in connection with the use or inability to use this product.